	7	6	5	4	3		2		
	NOTES: UNLESS OTHERWISE SPECIFIED  1 Rohs Compliant Assembly Required. Assemble per IPC—A—6  2 AQUEOUS BASED CLEANING AFTER SOLDER FOR ALL COMPONEN Rohs Solder Process is acceptable.  3 ITEM IDENTIFICATION: MARK REVISION NUMBER OF THIS DRAWING	ITS IS PREFERRED, NO—CLEAN					DESCRIPTION  INITIAL RELEASE  REV BOX CHANGE, TRACES CHANGED	REVISIONS  DATE  07/21/2016  TO 0.2MM.  09/23/2016	APRVD
									C
В									В
				- 100868 SHE MINISTER SHEET REU HOUSING INTERCONNECT					
						APPROVALS  DESIGNER  F. PRICE  ENGINEER  D. BRUEY  MECH ENG  A. DAHLGREN	09/23/2016 1511 Sixth Av PRIN Hou	YNAPSE  ve. Suite 300, Seattle, WA 98101 206.381.0898  TED CIRCUIT BOARD ASSEMBLY sing Interconnect Board  00-100868  O2  SHEET 1	2
	7	6	5	4	3		2		

